



Product / Process Change Notice

No.: Z200-PCN-DM201504-02-A

Date: 04/13/2015

Change Title : W25Q80EW "E-Series" (90nm) to replace W25Q80BW "B-Series" (90nm) 8Mb 1.8V SpiFlash® Memories

Change Classification: Major Minor

Change item : Design Raw Material Wafer FAB Package Assembly Testing Others

Affected Product(s) :

W25Q80BWBWYIG, W25Q80BWSNIG, W25Q80BWSVIG, W25Q80BWUXIE, W25Q80BWZPIG

Description of Change(s)

The W25Q80EW 8Mb 1.8V SpiFlash® Memories use Winbond's 90nm Flash technology. It is function compatible W25Q80BW 90nm devices offering improved performance, features and availability.

Reason for Change(s) :

Improve features which as below,

- a) Command backward compatible with W25Q80BW (same Superset Instruction Set)
- b) Clock operation up to 104MHz
- c) Lower power consumption
- d) SPI with Single / Dual / Quad / QPI mode
- e) Flexible architecture with 4KB sectors

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change

Function : No Change

Reliability : No Concern (Please refer to attachment I)

Hazardous Substances: No Concern (Please refer to attachment II)

Qualification Plan/ Results :

Based on Winbond W25Q80EW Serial Flash Reliability report, the new product meets our criteria and no quality concern (refer to Attachment I in details)

Implementation Plan :

Please refer to attachment III in details.

Date Code: _____ onward Lot No: _____ onward Proposed first ship date: 07/01/2015



Originator: (QA Sec. Manager)	<i>YH Cheng</i>	Approval: (QA Dept. Manager)	<i>YH Cheng</i>	Approval: (QRA Director)	<i>Kevin Chen</i>
Contact for Questions & Concerns	Name: <u>Betty Huang</u> TEL: <u>886-3-5678168</u> (ext.86549) FAX: <u>886-3-5796124</u> Address : <u># 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan</u> E-mail: <u>Hyhuang8@winbond.com</u>				

Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

<input type="checkbox"/> Approval <input type="checkbox"/> Disapproval <input type="checkbox"/> Conditional Approval : _____
Comment:
Date: _____
Dept. name: _____
Person in charge: _____



Winbond Electronics Corporation

No.539, Sec.2 Wenxing Rd.
Jhubei City, Hsinchu,
Taiwan, R.O.C.

Product Obsolescence Notice

W25Q80EW SpiFlash Memories

Notification Date: March 30, 2015

Dear Valued Customer,

This letter is to notify you of Winbond’s intention to terminate production of the W25Q80BW SpiFlash memory. And replace it with the W25Q80EW. Replacement part numbers are listed below:

Winbond Current PN (90nm B-Series)	Winbond Primary Replacement PN (90nm E-Series)
W25Q80BWSNIG	W25Q80EWSNIG
W25Q80BWSVIG	W25Q80EWSVIG
W25Q80BWZPIG	W25Q80EWZPIG
W25Q80BWUXIE	W25Q80EWUXIE
W25Q80BWBYIG	W25Q80EWBYIG

The W25Q80EW device features:

Features

- a) Command backward compatible with W25Q80BW (same Superset Instruction Set)
- b) Clock operation up to 104MHz
- c) Lower power consumption
- d) SPI with Single / Dual / Quad / QPI mode
- e) Flexible architecture with 4KB sectors

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W25Q80BW	Apr./01/2015	Oct./01/2015	Apr./01/2016	W25Q80EW	Mar./16/2015	Apr./01/2015

Eddy Hung
Assistant Vice President of Flash Marketing